

MECHANICAL CASE OUTLINE

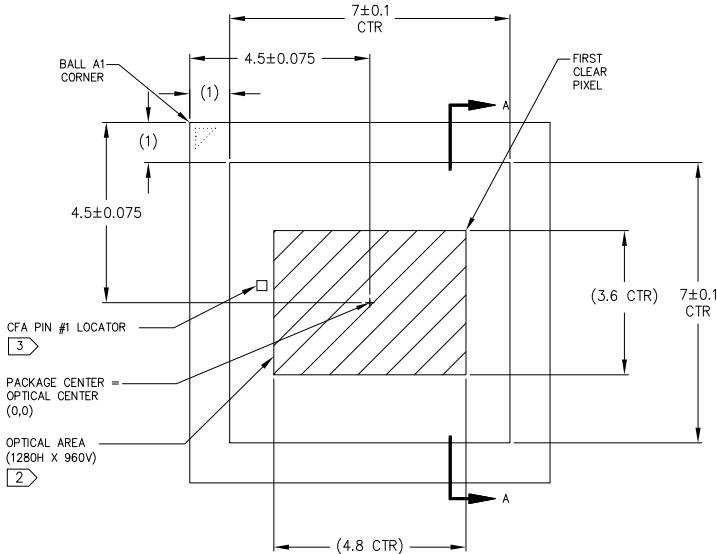
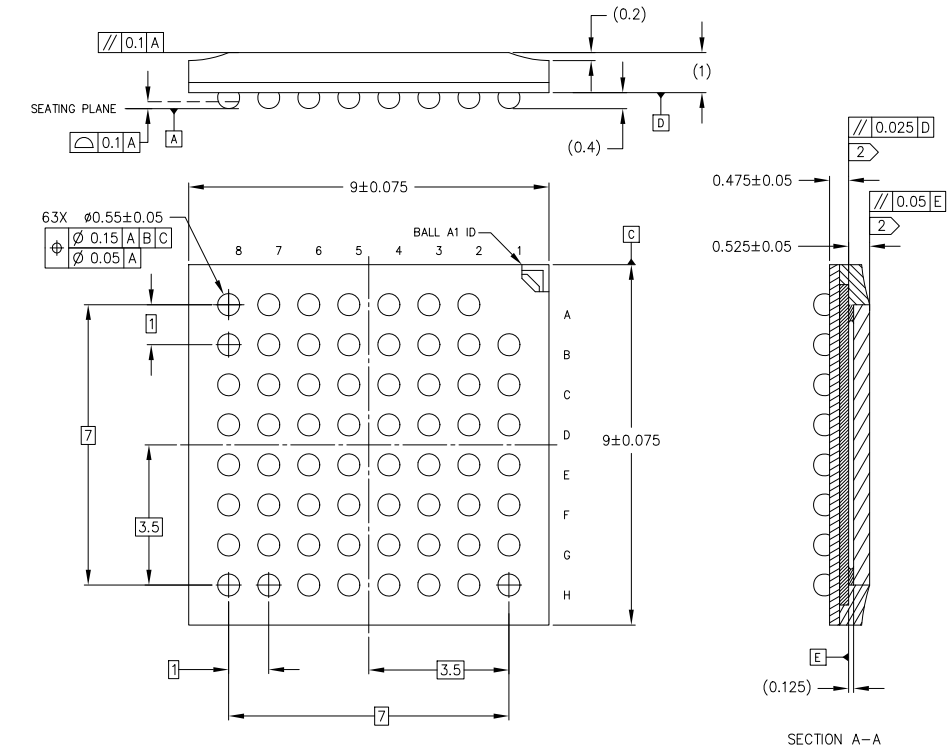
PACKAGE DIMENSIONS

ON Semiconductor®



IBGA63 9x9 CASE 503AF ISSUE O

DATE 30 DEC 2014



NOTES	
1	DIMENSIONS IN MM. DIMENSIONS IN () ARE FOR REFERENCE ONLY.
2	MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO PACKAGE EDGES: 1°; MAXIMUM TILT OF OPTICAL AREA RELATIVE TO SUBSTRATE PLANE [D]: 25 MICRONS. MAXIMUM TILT OF COVER GLASS RELATIVE TO OPTICAL AREA PLANE [E]: 50 MICRONS.
3	CFA PIN #1 LOCATOR FROM DIE CENTER: (X1= -2821.050, Y1=553.930) & (X2 =-2571.420, Y2=304.300)

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